

RECEIVED  
CENTRAL FAX CENTER

JUL 12 2004

OFFICIAL

Appl. No. 09/752,360  
Amdt. dated July 12, 2004  
Reply to Office Action of March 1, 2004.

AMENDMENTS IN THE CLAIMS

Claims 14-22 were withdrawn from further consideration pursuant to 37 CFR 1.142(b) as being drawn to a non-elected invention. Please amend claims 10, 12 and 13 as set forth in the following listing of the claims.

1. (previously presented) A planarized ultra fine particle film forming method for forming a planarized ultra fine particle film from a deposited film of ultra fine particles, comprising the steps of: supplying the ultra fine particles to a substrate to form the deposited film of ultra fine particles, and planarizing a surface of the deposited film of the ultra fine particles supplied to the substrate.

2. (original) A planarized ultra fine particle film forming method according to claim 1, wherein the ultra fine particles are ceramic or metal ultra fine particles.

3. (original) A planarized ultra fine particle film forming method according to claim 1, wherein said planarizing step rolls, scrapes, grinds or

polishes a surface layer portion of the deposited film of the ultra fine particles supplied to the substrate.

4. (original) A planarized ultra fine particle film forming method according to claim 1, wherein said planarizing step presses a surface layer portion of the deposited film of the ultra fine particles supplied to the substrate.

5. (previously presented) A planarized ultra fine particle film forming method according to claim 1, wherein the deposited film is applied with a mechanical impulse force, which is equal to or greater than Vickers hardness of the ultra fine particles, to the ultra fine particles supplied to the substrate to crush the ultra fine particles and make the particles bond together.

6. (previously presented) A planarized ultra fine particle film forming method according to claim 5, wherein the mechanical impact force is applied to the deposited film: by accelerating ultra fine particles by an electrostatic field or gas transport and spraying the particles to and colliding the particles with the ultra fine particles on the substrate; by using a brush or roller rotating at high speed, a pressure needle moving up and down at high speed, or a piston moving at high speed by explosion force; or by generating ultrasonic sounds.

7. (previously presented) A planarized ultra fine particle film forming method according to claim 5, wherein in accordance with the mechanical impact force to be applied to the ultra fine particles, the ultra fine particles are processed by a processing step enabling the ultra fine particles to be easily crushed with the mechanical impact force in excess of a mechanical strength or a brittle fracture strength of the ultra fine particles.

8. (previously presented) A planarized ultra fine particle film forming method according to claim 7, wherein the processing step of the ultra fine particles includes a process of the following group of processes: adjusting a preliminary baking temperature of source ultra fine particles; heating ultra fine particles prepared to have a particle diameter of about several tens nm and aggregating the particles to form secondary particles having a particle diameter of about 50 nm to 1  $\mu$ m; or forming cracks in ultra fine particles so as to make the particles easy to be crushed, by using a milling apparatus, a breaker, a crusher, a ball mill, a jet mill, a vibration mill, an epicyclic mill and a bead mill.

9. (previously presented) A planarized ultra fine particle film forming method according to claim 1, wherein the deposited film is formed by a further step of applying an ion beam or plasma to the ultra fine particles supplied to the substrate.

10. (currently amended) A planarized ultra fine particle film forming apparatus for forming a planarized ultra fine particle film from a deposited film of a single layer structure or of a multi-layer structure of ultra fine particles, which deposited film is formed by supplying the ultra fine particles to a substrate, the apparatus comprising: means for applying the ultra fine particles to the substrate, and means for planarizing a surface of the deposited film, the planarizing means including at least one of the following planarizing devices: an attached particle removal apparatus for rolling or scraping a surface layer portion of the deposited film of the ultra fine particles supplied to the substrate; a film surface processing apparatus for grinding or polishing the surface layer portion; and a pressure apparatus for pressing the deposited film.

11. (original) A planarized ultra fine particle film forming apparatus according to claim 10, wherein the substrate and said attached particle removal apparatus or said film surface processing apparatus are structured to be movable relative to each other.

12. (currently amended) ~~A~~  
~~planarized ultra fine particle film forming apparatus~~  
~~according to claim 10, further comprising~~ A planarized ultra  
fine particle film forming apparatus for forming a  
planarized ultra fine particle film from a deposited film of  
ultra fine particles, which deposited film is formed by

supplying the ultra fine particles to a substrate, the apparatus comprising: means for applying the ultra fine particles to the substrate, and means for planarizing a surface of the deposited film, the planarizing means including at least one of the following planarizing devices: an attached particle removal apparatus for rolling or scraping a surface layer portion of the deposited film of the ultra fine particles supplied to the substrate; a film surface processing apparatus for grinding or polishing the surface layer portion; and a pressure apparatus for pressing the deposited film; wherein the apparatus further comprises a mechanical impact force, which is equal to or higher than Vickers hardness of the ultra fine particles, loading apparatus for loading a mechanical impact force to the ultra fine patterns of the deposited film.

13. (currently amended) \*

planarized ultra fine particle film forming apparatus according to claim 10, further comprising A planarized ultra fine particle film forming apparatus for forming a planarized ultra fine particle film from a deposited film of ultra fine particles, which deposited film is formed by supplying the ultra fine particles to a substrate, the apparatus comprising: means for applying the ultra fine particles to the substrate, and means for planarizing a surface of the deposited film, the planarizing means including at least one of the following planarizing devices: an attached particle removal apparatus for rolling or scraping a surface layer portion of the deposited film of the ultra fine particles supplied to the substrate; a film

surface processing apparatus for grinding or polishing the surface layer portion; and a pressure apparatus for pressing the deposited film; wherein the apparatus further comprises a radiation apparatus for radiating an ion beam or plasma to the ultra fine patterns of the deposited film.

14. (withdrawn) A planarized ultra fine particle film forming method for forming a planarized ultra fine particle film from a deposited film of ultra fine particles formed by supplying the ultra fine particles to a substrate, the method comprising one or more of a planarizing step of planarizing a surface of the deposited film of the ultra fine particles by blowing planarizing fine particles having a grinding/polishing function at an oblique incidence angle toward the surface of the deposited film.

15. (withdrawn) A planarized ultra fine particle film forming method according to claim 14, wherein the planarizing fine particles are accelerated by using an electrostatic field or gas and blown toward the surface of the deposited film of the ultra fine patterns.

16. (withdrawn) A planarized ultra fine particle film forming method according to claim 14, wherein the incidence angle of a flow of the planarizing fine particles relative to the substrate is in a range of - 60 degrees to - 5 degrees or + 5 degrees to + 60 degrees.

17. (withdrawn) A planarized ultra fine particle film forming method according to claim 14, wherein the planarizing fine particles have a same composition as that of the ultra fine particles.

18. (withdrawn) A planarized ultra fine particle film forming method according to claim 14, wherein the planarizing fine particles have a particle diameter larger than that of the ultra fine particles.

19. (withdrawn) A planarized ultra fine particle film forming method according to claim 14, wherein the planarizing fine particles have a rigidity higher than that of the ultra fine particles.

20. (withdrawn) A planarized ultra fine particle film forming apparatus for forming a planarized ultra fine particle film from a deposited film of ultra fine particles formed by supplying the ultra fine particles to a substrate, wherein planarizing fine particles having a grinding/polishing function are blown at an oblique incidence angle toward the surface of the deposited film.

21. (withdrawn) A planarized ultra fine particle film forming apparatus according to claim 20, further comprising a spray apparatus such as a nozzle and an electrostatic acceleration gun for jetting out, at the same

time or separately, the ultra fine particles and the planarizing having the grinding/polishing function, toward the substrate, and a center axis of a jet flow of said spray apparatus being set in an incidence angle range of - 60 degrees to - 5 degrees or + 5 degrees to + 60 degrees relative to a surface of the substrate.

22. (withdrawn) A planarized ultra fine particle film forming apparatus according to claim 20, further comprising a spray apparatus such as a nozzle and an electrostatic acceleration gun for jetting out, at the same time or separately, the ultra fine particles and the planarizing having the grinding/polishing function, toward the substrate, and a flow of the ultra fine particles or planarizing particles jetted out from said spray apparatus being set to have a conical shape having an incidence angle range of - 60 degrees to - 5 degrees or + 5 degrees to + 60 degrees about a center axis of a jet flow of said spray apparatus.